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Amendments to the Claims

This listing will replace all prior versions and listings of claims in the application:

Listing of Claims

1. (original) A method of depositing a film of a metal chalcogenide, comprising the steps of:

contacting an isolated hydrazinium-based precursor of a metal chalcogenide and a solvent having therein a solubilizing additive to form a solution of a complex thereof;

applying said solution of said complex onto a substrate to produce a coating of said solution on said substrate;

removing said solvent from said coating to produce a film of said complex on said substrate; and thereafter

annealing said film of said complex to produce a metal chalcogenide film on said substrate.

2. (original) The method of claim 1, wherein said solvent is selected from the group consisting of: water, lower alcohol, ether, esters, alkylene glycol of 2-6 carbon atoms, dialkylene glycol of 4-6 carbon atoms, trialkylene glycol of 6 carbon atoms, glyme, diglyme, triglyme, propylene glycol monoacetate, DMSO, DMF, DMA, HMPA and a mixture thereof.

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- 3. (original) The method of claim 2, wherein said solubilizing additive is selected from the group consisting of: an aliphatic amine of 1-10 carbon atoms, aromatic amine of 4-10 carbon atoms, aminoalcohol of 2-6 carbon atoms and a mixture thereof.
- 4. (original) The method of claim 2, wherein said solubilizing additive is selected from the group consisting of: n-propylamine, iso-propylamine, n-butylamine, sec-butylamine, iso-butylamine, pentylamine, n-hexylamine, cyclohexylamine, phenethylamine, pyridine, aniline, aminotoluene, ethanolamine, propanolamine, diethanolamine, dipropanolamine, triethanolamine, tripropanolamine and a mixture thereof.
- 5. (original) The method of claim 1, wherein said isolated hydrazinium-based precursor of said metal chalcogenide is prepared by a process comprising the steps of:

contacting: at least one metal chalcogenide, a hydrazine compound represented by the formula:

R¹R²N-NR³R⁴

wherein each of R¹, R², R³ and R⁴ is independently selected from the group consisting of: hydrogen, aryl, methyl, ethyl and a linear, branched or cyclic alkyl of 3-6 carbon atoms, and optionally an elemental chalcogen selected from the group consisting of: S, Se, Te and a combination thereof, to produce a solution of a hydrazinium-based precursor of said metal chalcogenide in said hydrazine compound; and

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isolating hydrazinium-based precursor of said metal chalcogenide as a substantially pure product.

- 6. (original) The method of claim 5, wherein said metal chalcogenide comprises a metal selected from the group consisting of: Ge, Sn, Pb, Sb, Bi, Ga, In, TI and a combination thereof and a chalcogen selected from the group consisting of: S, Se, Te and a combination thereof.
- 7. (original) The method of claim 5, wherein said metal chalcogenide is represented by the formula MX or MX₂ wherein M is a metal selected from the group consisting of: Ge, Sn, Pb and a combination thereof; and wherein X is a chalcogen selected from the group consisting of: S, Se, Te and a combination thereof.
- 8. (original) The method of claim 5, wherein said metal chalcogenide is represented by the formula M₂X₃ wherein M is a metal selected from the group consisting of: Sb, Bi, Ga, In and a combination thereof; and wherein X is a chalcogen selected from the group consisting of: S, Se, Te and a combination thereof.
- 9. (original) The method of claim 5, wherein said metal chalcogenide is represented by the formula M_2X wherein M is TI; and wherein X is a chalcogen selected from the group consisting of: S, Se, Te and a combination thereof.

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10. (original) The method of claim 5, wherein said metal is selected from the group consisting of: Sn and Sb; and wherein said chalcogen is selected from the group consisting of: S and Se.

11. (original) The method of claim 10, wherein said chalcogenide is represented by the formula:

$$Sn(S_{2-x}Se_x)$$

wherein x is from 0 to 2.

- 12. (original) The method of claim 5, wherein each of R^1 , R^2 , R^3 and R^4 is independently selected from the group consisting of: hydrogen, aryl, methyl and ethyl.
- 13. (original) The method of claim 5, wherein R^1 , R^2 , R^3 and R^4 are hydrogen.
- 14. (original) The method of claim 5, wherein said metal chalcogenide film is in the form of a thin film.
- 15. (original) The method of claim 5, wherein said metal chalcogenide film comprises a polycrystalline metal chalcogenide or single crystals of said metal chalcogenide.

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- 16. (original) The method of claim 15, wherein said polycrystalline metal chalcogenide has a grain size equal to or greater than the dimensions between contacts in a semiconductor device.
- 17. (original) The method of claim 5, wherein said annealing step is carried out at a temperature and for a length of time sufficient to produce said metal chalcogenide film.
- 18. (original) The method of claim 1, wherein said substrate is selected from the group consisting of:

Kapton, polycarbonate, silicon, amorphous hydrogenated silicon, silicon carbide (SiC), silicon dioxide (SiO₂), quartz, sapphire, glass, metal, diamond-like carbon, hydrogenated diamond-like carbon, gallium nitride, gallium arsenide, germanium, silicon-germanium, indium tin oxide, boron carbide, boron nitride, silicon nitride (Si₃N₄), alumina (Al₂O₃), cerium(IV) oxide (CeO₂), tin oxide (SnO₂), zinc titanate (ZnTiO₂), a plastic material and a combination thereof.

- 19. (original) A film prepared by the method of claim 5.
- 20. (original) The method of claim 1, wherein said hydrazinium-based precursor of said metal chalcogenide is prepared by a process comprising the steps of:

contacting: at least one metal chalcogenide and a salt of an amine compound with H_2S , H_2Se or H_2Te , wherein said amine compound is represented by the formula:

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NR⁵R⁶R⁷

wherein each of R⁵, R⁶ and R⁷ is independently selected from the group consisting of: hydrogen, aryl, methyl, ethyl and a linear, branched or cyclic alkyl of 3-6 carbon atoms, to produce an ammonium-based precursor of said metal chalcogenide;

contacting said ammonium-based precursor of said metal chalcogenide, a hydrazine compound represented by the formula:

$R^1R^2N-NR^3R^4$

wherein each of R¹, R², R³ and R⁴ is independently selected from the group consisting of: hydrogen, aryl, methyl, ethyl and a linear, branched or cyclic alkyl of 3-6 carbon atoms, and optionally, an elemental chalcogen selected from the group consisting of: S, Se, Te and a combination thereof; to produce a solution of a hydrazinium-based precursor of said metal chalcogenide in said hydrazine compound; and

isolating hydrazinium-based precursor of said metal chalcogenide as a substantially pure product.

21. (original) The method of claim 20, wherein said metal chalcogenide comprises a metal selected from the group consisting of: Ge, Sn, Pb, Sb, Bi, Ga, In, Tl and a combination thereof and a chalcogen selected from the group consisting of: S, Se, Te and a combination thereof.

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- 22. (original) The method of claim 20, wherein each of R^1 , R^2 , R^3 , R^4 , R^5 , R^6 and R^7 is independently selected from the group consisting of: hydrogen, aryl, methyl and ethyl.
- 23. (original) The method of claim 20, wherein R^1 , R^2 , R^3 , R^4 , R^5 , R^6 and R^7 are hydrogens.
- 24. (original) The method of claim 20, wherein said metal chalcogenide film is in the form of a thin film.
- 25. (original) The method of claim 20, wherein said metal chalcogenide film comprises a polycrystalline metal chalcogenide or single crystals of said metal chalcogenide.
- 26. (original) The method of claim 25, wherein said polycrystalline metal chalcogenide has a grain size equal to or greater than the dimensions between contacts in a semiconductor device.
- 27. (original) The method of claim 20, wherein said annealing step is carried out at a temperature and for a length of time sufficient to produce said metal chalcogenide film.
- 28. (original) The method of claim 20, wherein said substrate is selected from the group consisting of:

Kapton, polycarbonate, silicon, amorphous hydrogenated silicon, silicon carbide (SiC), silicon dioxide (SiO₂), quartz, sapphire, glass, metal,

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diamond-like carbon, hydrogenated diamond-like carbon, gallium nitride, gallium arsenide, germanium, silicon-germanium, indium tin oxide, boron carbide, boron nitride, silicon nitride (Si₃N₄), alumina (Al₂O₃), cerium(IV) oxide (CeO₂), tin oxide (SnO₂), zinc titanate (ZnTiO₂), a plastic material and a combination thereof.

29. (original) A film prepared by the method of claim 20.

30. (original) A method of forming a field-effect transistor of the type having a source region and a drain region, a channel layer extending between the source region and the drain region, the channel layer including a semiconducting material, a gate region disposed in spaced adjacency to the channel layer, an electrically insulating layer between the gate region and the source region, drain region and channel layer, comprising:

preparing a channel layer comprising a film of a metal chalcogenide semiconducting material by a method comprising the steps of: contacting an isolated hydrazinium-based precursor of a metal chalcogenide and a solvent having therein a solubilizing additive to form a solution of a complex thereof; applying said solution of said complex onto a substrate to produce a coating of said solution on said substrate; removing said solvent from said coating to produce a film of said complex on said substrate; and thereafter annealing said film of said complex to produce a metal chalcogenide film on said substrate.

31. (original) The method of claim 30, wherein said source region, channel layer and drain region are disposed upon a surface of a substrate, said electrically insulating layer is disposed over said channel layer and

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extending from said source region to said drain region, and said gate region is disposed over said electrically insulating layer.

- 32. (original) The method of claim 30, wherein said gate region is disposed as a gate layer upon a surface of a substrate, said electrically insulating layer is disposed upon said gate layer, and said source region, channel layer, and drain region are disposed upon said electrically insulating layer.
- 33. (original) The method of claim 30, wherein said metal chalcogenide film is in the form of a thin film having a thickness of from about 5 Å to about 2,000 Å.
- 34. (original) The method of claim 30, wherein said metal chalcogenide film comprises a polycrystalline metal chalcogenide or single crystals of said metal chalcogenide.
- 35. (original) The method of claim 34, wherein said metal chalcogenide film is polycrystalline with a grain size equal to or greater than the dimensions between contacts in a semiconductor device.
- 36. (original) The method of claim 30, wherein said metal chalcogenide comprises a metal selected from the group consisting of: Ge, Sn, Pb, Sb, Bi, Ga, In, Tl and a combination thereof and a chalcogen selected from the group consisting of: S, Se, Te and a combination thereof.

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37. (original) The method of claim 30, wherein said annealing step is carried out at a temperature and for a length of time sufficient to produce said metal chalcogenide film.

38. (original) The method of claim 37, wherein said temperature is from about 25 °C to about 500 °C.

39. (original) The method of claim 38, wherein said temperature is from about 250 °C to about 350 °C.

40. (original) The method of claim 30, wherein said substrate is selected from the group consisting of:

Kapton, polycarbonate, silicon, amorphous hydrogenated silicon, silicon carbide (SiC), silicon dioxide (SiO₂), quartz, sapphire, glass, metal, diamond-like carbon, hydrogenated diamond-like carbon, gallium nitride, gallium arsenide, germanium, silicon-germanium, indium tin oxide, boron carbide, boron nitride, silicon nitride (Si₃N₄), alumina (Al₂O₃), cerium(IV) oxide (CeO₂), tin oxide (SnO₂), zinc titanate (ZnTiO₂), a plastic material and a combination thereof.

- 41. (original) A field-effect transistor prepared by the method of claim 30.
- 42. (original) A process for preparing an isolated hydrazinium-based precursor of a metal chalcogenide comprising the steps of:

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contacting: at least one metal chalcogenide, a hydrazine compound represented by the formula:

R¹R²N-NR³R⁴

wherein each of R¹, R², R³ and R⁴ is independently selected from the group consisting of: hydrogen, aryl, methyl, ethyl and a linear, branched or cyclic alkyl of 3-6 carbon atoms, and optionally an elemental chalcogen selected from the group consisting of: S, Se, Te and a combination thereof, to produce a solution of a hydrazinium-based precursor of said metal chalcogenide in said hydrazine compound; and

isolating the hydrazinium-based precursor of said metal chalcogenide as a substantially pure product.

- 43. (original) A hydrazinium metal chalcogenide prepared by the process of claim 42.
- 44. (original) A process for preparing an isolated hydrazinium-based precursor of a metal chalcogenide comprising the steps of:

contacting: at least one metal chalcogenide and a salt of an amine compound with H₂S, H₂Se or H₂Te, wherein said amine compound is represented by the formula:

NR⁵R⁶R⁷

wherein each of R⁵, R⁶ and R⁷ is independently selected from the group consisting of: hydrogen, aryl, methyl, ethyl and a linear, branched or cyclic

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alkyl of 3-6 carbon atoms, to produce an ammonium-based precursor of said metal chalcogenide;

contacting said ammonium-based precursor of said metal chalcogenide, a hydrazine compound represented by the formula:

R¹R²N-NR³R⁴

wherein each of R¹, R², R³ and R⁴ is independently selected from the group consisting of: hydrogen, aryl, methyl, ethyl and a linear, branched or cyclic alkyl of 3-6 carbon atoms, and optionally, an elemental chalcogen selected from the group consisting of: S, Se, Te and a combination thereof; to produce a solution of a hydrazinium-based precursor of said metal chalcogenide in said hydrazine compound; and

isolating hydrazinium-based precursor of said metal chalcogenide as a substantially pure product.

45. (original) A hydrazinium metal chalcogenide prepared by the process of claim 44.

46. (original) A hydrazinium metal chalcogenide represented by the formula:

$$M_z X_0 (R^1 R^2 N - N H R^3 R^4)_{2q-nz} (R^1 R^2 N - N R^3 R^4)_m$$

wherein:

M is a main-group metal having a valence n, wherein n is an integer from 1 to 6;

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X is a chalcogen;

z is an integer from 1 to 10;

g is an integer from 1 to 30;

m is from 1 to 30.5; and

each of R¹, R², R³ and R⁴ is independently selected from the group consisting of: hydrogen, aryl, methyl, ethyl and a linear, branched or cyclic alkyl of 3-6 carbon atoms.

- 47. (original) The hydrazinium metal chalcogenide of claim 46, wherein said metal is selected from the group consisting of: Ge, Sn, Pb, Sb, Bi, Ga, In and Tl.
- 48. (original) The hydrazinium metal chalcogenide of claim 46, wherein said chalcogen is selected from the group consisting of: S, Se and Te.
 - 49. (original) A film prepared by the method of claim 1.
- -- 50. (new) A method of preparing a multilayer film on a substrate, said multilayer film having a plurality of metal chalcogenide films; wherein each of said metal chalcogenide films is prepared by a method comprising the steps of:
- (a) contacting an isolated hydrazinium-based precursor of a metal chalcogenide and a solvent having therein a solubilizing additive to form a solution of a complex thereof;
- (b) applying said solution of said complex onto a substrate to produce a coating of said solution on said substrate;

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- (c) removing said solvent from said coating to produce a film of said complex on said substrate; and thereafter
- (d) annealing said film of said complex to produce a metal chalcogenide film on said substrate; and
- (e) repeating steps (a), (b), (c) and (d) with the same or different chalcogenide to produce said multilayer film.
- 51. (new) The method of claim 50, wherein said isolated hydrazinium-based precursor is represented by the formula:

$$M_z X_q (R^1 R^2 N - NHR^3 R^4)_{2q-nz} (R^1 R^2 N - NR^3 R^4)_m$$

wherein:

M is a main-group metal having a valence n, wherein n is an integer from 1 to 6;

X is a chalcogen;

z is an integer from 1 to 10;

q is an integer from 1 to 30;

m is from 1 to 30.5; and

each of R¹, R², R³ and R⁴ is independently selected from the group consisting of: hydrogen, aryl, methyl, ethyl and a linear, branched or cyclic alkyl of 3-6 carbon atoms.

52. (new) The method of claim 50, wherein said metal is selected from the group consisting of: Ge, Sn, Pb, Sb, Bi, Ga, In and Tl.

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53. (new) The method of claim 50, wherein said chalcogenide is selected from the group consisting of: S, Se and Te.

54. (new) The method of claim 50, wherein said multilayer film comprises a plurality of two alternating metal chalcogenide films each selected from the group consisting of: SnSe₂, GeSe₂, In₂Se₃, Sb₂S₃, and Sb₂Se₃.

55. (new) The method of claim 50, wherein said metal chalcogenide film is produced at a temperature from about 25 °C to about 500 °C.

56. (new) The method of claim 50, wherein said substrate is selected from the group consisting of:

Kapton, silicon, amorphous hydrogenated silicon, silicon carbide (SiC), silicon dioxide (SiO₂), quartz, sapphire, glass, metal, diamond-like carbon, hydrogenated diamond-like carbon, gallium nitride, gallium arsenide, germanium, silicon-germanium, indium tin oxide, boron carbide, boron nitride, silicon nitride (Si₃N₄), alumina (Al₂O₃), cerium(IV) oxide (CeO₂), tin oxide (SnO₂), zinc titanate (ZnTiO₂), a plastic material and a combination thereof.

57. (new) A device comprising:

a multilayer active layer having a plurality of metal chalcogenide films; wherein each of said metal chalcogenite films is prepared by a method comprising steps of:

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- (a) contacting an isolated hydrazinium-based precursor of a metal chalcogenide and a solvent having therein a solubilizing additive to form a solution of a complex thereof;
- (b) applying said solution of said complex onto a substrate to produce a coating of said solution on said substrate;
- (c) removing said solvent from said coating to produce a film of said complex on said substrate; and thereafter
- (d) annealing said film of said complex to produce a metal chalcogenide film on said substrate; and
- (e) repeating steps (a), (b), (c) and (d) with the same or different chalcogenide to produce said multilayer film.
- 58. (new) The device of claim 57, wherein said isolated hydrazinium-based precursor is represented by the formula:

$$M_zX_a (R^1R^2N-NHR^3R^4)_{2a-nz} (R^1R^2N-NR^3R^4)_m$$

wherein:

M is a main-group metal having a valence n, wherein n is an integer from 1 to 6;

X is a chalcogen;

z is an integer from 1 to10;

q is an integer from 1 to 30;

m is from 1 to 30.5; and

each of R¹, R², R³ and R⁴ is independently selected from the group consisting of: hydrogen, aryl, methyl, ethyl and a linear, branched or cyclic alkyl of 3-6 carbon atoms.

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- 59. (new) The device of claim 57, wherein said metal is selected from the group consisting of: Ge, Sn, Pb, Sb, Bi, Ga, In and Tl.
- 60. (new) The device of claim 57, wherein said chalcogenide is selected from the group consisting of: S, Se and Te.
- 61. (new) The device of claim 57, wherein said multilayer film comprises a plurality of two alternating metal chalcogenide films each selected from the group consisting of: SnSe₂, GeSe₂, In₂Se₃, Sb₂S₃, and Sb₂Se₃.
- 62. (new) The device of claim 57, wherein said metal chalcogenide film is produced at a temperature from about 25 °C to about 500 °C.
- 63. (new) The device of claim 57, wherein said substrate is selected from the group consisting of:

Kapton, silicon, amorphous hydrogenated silicon, silicon carbide (SiC), silicon dioxide (SiO₂), quartz, sapphire, glass, metal, diamond-like carbon, hydrogenated diamond-like carbon, gallium nitride, gallium arsenide, germanium, silicon-germanium, indium tin oxide, boron carbide, boron nitride, silicon nitride (Si₃N₄), alumina (Al₂O₃), cerium(IV) oxide (CeO₂), tin oxide (SnO₂), zinc titanate (ZnTiO₂), a plastic material and a combination thereof.

64. (new) The device of claim 57, wherein said device is selected from the group consisting of: flat panel displays, non-linear optical devices, non-

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linear photo-conductive devices, chemical sensors, light-emitting diodes, thinfilm transistors, field-effect transistors, media for optical data storage, phase change media for optical data storage, solar cells and thermoelectric devices.

- 65. (new) A method of preparing a multilayer film on a substrate, said multilayer film having a plurality of metal chalcogenide films; wherein each of said metal chalcogenide films is prepared by a method comprising steps of:
- (a) contacting a metal chalcogenide and (i) a hydrazine compound, optionally in the presence of additional amount of an elemental chalcogen, or (ii) first a salt of an amine compound with H₂S, H₂Se or H₂Te, and thereafter a hydrazine compound, to produce a solution of a hydrazinium-based precursor of said metal chalcogenide;
- (b) applying said solution of said hydrazinium-based precursor of said metal chalcogenide onto a substrate to produce a film of said precursor;
- (c) annealing said film of said precursor under conditions sufficient to produce said metal chalcogenide film; and
- (d) repeating steps (a), (b) and (c) with the same or different chalcogenide to produce said multilayer film.
- 66. (new) The method of claim 65, wherein said metal is selected from the group consisting of: Ge, Sn, Pb, Sb, Bi, Ga, In and Tl.
- 67. (new) The method of claim 65, wherein said chalcogenide is selected from the group consisting of: S, Se and Te.
- 68. (new) The method of claim 65, wherein said multilayer film comprises a plurality of two alternating metal chalcogenide films each

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selected from the group consisting of: SnSe₂, GeSe₂, In₂Se₃, Sb₂S₃, and Sb₂Se₃.

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69. (new) The method of claim 65, wherein said hydrazine compound is represented by the formula:

$R^1R^2N-NR^3R^4$

wherein each of R¹, R², R³ and R⁴ is independently selected from the group consisting of: hydrogen, aryl, methyl, ethyl and a linear, branched or cyclic alkyl of 3-6 carbon atoms; and wherein said amine compound is represented by the formula:

NR5R6R7

wherein each of R⁵, R⁶ and R⁷ is independently selected from the group consisting of: hydrogen, aryl, methyl, ethyl and a linear, branched or cyclic alkyl of 3-6 carbon atoms.

- 70. (new) The method of claim 65, wherein said metal chalcogenide film is produced at a temperature from about 25 °C to about 500 °C.
- 71. (new) The method of claim 65, wherein said substrate is selected from the group consisting of:

Kapton, silicon, amorphous hydrogenated silicon, silicon carbide (SiC), silicon dioxide (SiO₂), quartz, sapphire, glass, metal, diamond-like carbon,

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hydrogenated diamond-like carbon, gallium nitride, gallium arsenide, germanium, silicon-germanium, indium tin oxide, boron carbide, boron nitride, silicon nitride (Si_3N_4), alumina (Al_2O_3), cerium(IV) oxide (CeO_2), tin oxide (SnO_2), zinc titanate ($ZnTiO_2$), a plastic material and a combination thereof.

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72. (new) A device comprising:

a multilayer active layer having a plurality of metal chalcogenide films; wherein each of said metal chalcogenite films is prepared by a method comprising steps of:

- (a) contacting a metal chalcogenide and (i) a hydrazine compound, optionally in the presence of additional amount of an elemental chalcogen, or (ii) first a salt of an amine compound with H₂S, H₂Se or H₂Te, and thereafter a hydrazine compound, to produce a solution of a hydrazinium-based precursor of said metal chalcogenide;
- (b) applying said solution of said hydrazinium-based precursor of said metal chalcogenide onto a substrate to produce a film of said precursor;
- (c) annealing said film of said precursor under conditions sufficient to produce said metal chalcogenide film; and
- (d) repeating steps (a), (b) and (c) with the same or different chalcogenide to produce said multilayer active layer in said device.
- 73. (new) The device of claim 72, wherein said metal is selected from the group consisting of: Ge, Sn, Pb, Sb, Bi, Ga, In and Tl.
- 74. (new) The device of claim 72, wherein said chalcogenide is selected from the group consisting of: S, Se and Te.

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75. (new) The device of claim 72, wherein said multilayer film comprises a plurality of two alternating metal chalcogenide films each selected from the group consisting of: SnSe₂, GeSe₂, In₂Se₃, Sb₂S₃, and Sb₂Se₃.

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76. (new) The device of claim 72, wherein said hydrazine compound is represented by the formula:

$R^1R^2N-NR^3R^4$

wherein each of R¹, R², R³ and R⁴ is independently selected from the group consisting of: hydrogen, aryl, methyl, ethyl and a linear, branched or cyclic alkyl of 3-6 carbon atoms; and wherein said amine compound is represented by the formula:

NR⁵R⁶R⁷

wherein each of R⁵, R⁶ and R⁷ is independently selected from the group consisting of: hydrogen, aryl, methyl, ethyl and a linear, branched or cyclic alkyl of 3-6 carbon atoms.

- 77. (new) The device of claim 72, wherein said metal chalcogenide film is produced at a temperature from about 25 °C to about 500 °C.
- 78. (new) The device of claim 72, wherein said substrate is selected from the group consisting of:

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Kapton, silicon, amorphous hydrogenated silicon, silicon carbide (SiC), silicon dioxide (SiO₂), quartz, sapphire, glass, metal, diamond-like carbon, hydrogenated diamond-like carbon, gallium nitride, gallium arsenide, germanium, silicon-germanium, indium tin oxide, boron carbide, boron nitride, silicon nitride (Si₃N₄), alumina (Al₂O₃), cerium(IV) oxide (CeO₂), tin oxide (SnO₂), zinc titanate (ZnTiO₂), a plastic material and a combination thereof.

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79. (new) The device of claim 72, wherein said device is selected from the group consisting of: flat panel displays, non-linear optical devices, non-linear photo-conductive devices, chemical sensors, light-emitting diodes, thin-film transistors, field-effect transistors, media for optical data storage, phase change media for optical data storage, solar cells and thermoelectric devices.--